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(71) Applicant: **NEC CORP**

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(72) Inventor: **TANAKA MASASHI**

(54) **SEMICONDUCTOR DEVICE**

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(57) Abstract:

**PURPOSE:** To connect pads of two IC chips having a different chip size and a different function like a gate array with each other on front and rear sides of a lead to be stacked and mount ICs with higher density than usual.

**CONSTITUTION:** An IC chip 1 having a certain function is connected with an IC chip 2 that has a different function from this IC chip 1, and that an arrangement of pads has a mirror surface relation on front and rear sides of a lead, and the device is sealed with a lid 5 made of resin. In order not to simultaneously input same signals into two chips 1, 2, an AND circuit is provided between an input/output buffer and the pad, and the signals are transmitted into only the input buffer of one chip according to a chip selecting signal.

